

S-1 STEERING COMMITTEE MINUTES
Holiday Inn San Diego Bayside
4875 North Harbor Drive
San Diego, CA 92106

1.0 Call to Order - Circulate Membership Roster

Meeting called to order at 8:05 am by Chairman Mike Lauri

2.0 Committee Organization and Procedures

2.1 Membership Intros were conducted and Roster Circulated.

The attendance was as follows:

<u>NAME</u>	<u>COMPANY</u>
Michael Lauri	IBM
Paul Krystek	IBM via Phone
Dave Richardson	Vishay
Dave Toomey	Vishay
Jack Culloton	Vishay
Will Cantrell	Bourns
Jack McCullen	Intel
Bill Gisseler	TDK
Mike Cannon	TDK
Chris Reynolds	AVX
Sucha Viridi	ATC
Paul Bennett	RMD Instruments
Carl Lindquist	SOC America Inc.
Jayson Young	Kemet Electronics
Liwu Wang	Aemiluc
Laird Macomber	Cornell Dubilier
Michael Griffith	KOA Speer
Joe Biernacki	Stackpole Electronics
Dave Ritchey	Yageo Corp
Mary Carter Berrios	Kemet Electronics
Ed Mikoski	ECA

A quorum was present.

<u>Member Organizations Present</u>	<u>Present at this Meeting (Spring 2007)</u>	<u>Present at this meeting (Fall 2006)</u>	<u>Present at Spring 2006 Meeting</u>
ATC	Y	Y	Y
AVX	Y	Y	N
Cornell Dubilier	Y	Y	Y
IBM	Y	Y	Y
Intel	Y	Y	Y
Kemet	Y	Y	Y
KOA Speer Electronics	Y	Y	Y
SOC America Inc.	Y	Y	Y

SEI Electronics	Y	Y	Y
TDK	Y	Y	Y
Vishay	Y	Y	Y
Yageo	Y	Y	Y

Member Organizations Absent	Present at this meeting?(Spring 2007)	Present at this meeting? (Fall 2006)	Present at Spring 2006 Meeting
Cooper Bussmann	N	N	Y
Murata Electronics	N	Y	Y
Panasonic	N	Y	Y
Rohm Electronics	N	N	Y
Epcos	N	Y	Y
Mini-Systems Inc	N	Y	Y

Other Organizations Present
ECA
RMD Instruments

2.2 Approval of Agenda and Previous Minutes – Approved. Minutes need revision. JEITA was miss spelled, and next meeting is not in Washington DC, but in San Diego Ca.

2.3 Correspondance – Mike Griffin of KOA discussed the need for a component bulletin on the subject of Environmental Friendly Use Period (EFUP). Discussion centered around setting the number to 50 years. Mike will draft a bulletin for review at the next meeting. A PN will be issued for this new document.

S1 received correspondence from Scott Carter of the ACH committee to review the usage of EIA-383 and EIA-519. Chairmen surveyed the entire S1 committee membership and no one is referencing or using these specifications. The committee voted to archive both specs, and it passed unanimously.

2.4 Review of Committees Scope- To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

3.0 ECA Update/Presentations - Ed Mikoski gave an update on all the EIA environmental issues including the Berry agreement and on other trade activities. ECA discussed the P4 mechanical outline website and how to use it, along with what links will be later in the process linking the P4 outlines to the eventual manufactures websites. This work effort and continues to move forward.

ECA also gave a brief overview of the ECA message board, how it is being used today and where they want to take it moving forward. This will become a part of the specification commenting process in the near future.

4.0 Presentations

4.1 Paul Bennett Applications engineer for RMD Instruments gave a presentation on XRF analyzers for Rohs screening of materials. Paul discussed how the XRF detection works, its main features, and how it analyzes elements into K shell, L shell type elements. RMD uses a collimator to reduce the aperture X-ray size to analyze a smaller area of the sample taken. It's a screening

process only, not a quantitative measurement of concentrations. Samples need to be further analyzed by wet chemical analysis for quantitative purposes. XRF is going to be only a screening tool, not final analysis. Be aware that materials can be hidden and misidentified and you need to match the measurement areas to specimen size. Screening individual components will give better results than screening completed assemblies. A copy of the presentation will be posted on the ECA website.

5.0 Old Business

5.1 PN5149 – New joint standard on Assembly Processing, Evaluation and Classification of Non-IC Electronic Components Update – Paul Krystek via phone gave an update on the status of this new document. See the attached presentation provided. A straw-man document is in the works with a planned schedule to have a working document by the Fall engineering meetings. The sub-committee chairman plans on scheduling bi-weekly meeting to keep this specification progressing. Anyone interested in joining this sub-committee please send you name, company and contact information to Paul Krystek at IBM (pkrystek@us.ibm.com)

6.0 New Business

6.1 Kemet – Mary Carter-Berrios gave an update on the automotive qualification and change notification discussion. Automotive customers surveyed state that 80% of their problems are due to supplier process changes. They say there are 1500-2000 open a month, with 200-500 more submitted monthly. Automotive companies cannot keep up with these changes. This is impacting many of the suppliers in implementing changes. There is a change of PPAC manual changes to include even more divulging of more information about changes. Kemet is going to AEC to push for changes to the Q200 document in May at the AEC meetings.

6.2 Intel – Jack McCullen brought up that IPC/JEDEC (4-33 committee) is working on a halogen free document. It defines halogen free electronic components and PBC boards and is looking for anyone who has interest in working on it to contact Jack McCullen of Intel (jack.t.mccullen@intel.com)

7.0 Future Meetings – The next meeting is in San Antonio, TX in Sep 24-27, 2007 at the Holiday Inn Riverwalk. We voted on having the Spring 2007 meeting in Louisville, KY with backup in New Orleans.

8.0 Action Items –

ECA to issue a new PN for a bulletin on EFUP (M.Lauri to fillout Pins form)

9.0 Adjournment – Meeting was adjourned at 11:05AM.